



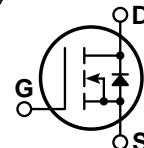
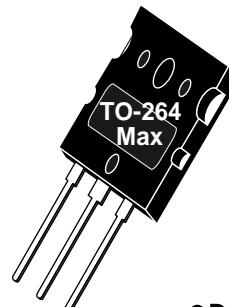
APT50M50L2FLL

500V 89A 0.050Ω

POWER MOS 7™

FREDFET

Power MOS 7™ is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS 7™ by significantly lowering $R_{DS(ON)}$ and Q_g . Power MOS 7™ combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with APT's patented metal gate structure.



- Lower Input Capacitance
- Increased Power Dissipation
- Lower Miller Capacitance
- Easier To Drive
- Lower Gate Charge, Q_g
- Popular TO-264 MAX Package

MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	APT50M50L2FLL	UNIT
V_{DSS}	Drain-Source Voltage	500	Volts
I_D	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	89	Amps
I_{DM}	Pulsed Drain Current ①	356	
V_{GS}	Gate-Source Voltage Continuous	±30	Volts
V_{GSM}	Gate-Source Voltage Transient	±40	
P_D	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	890	Watts
	Linear Derating Factor	7.12	W/°C
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C
T_L	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I_{AR}	Avalanche Current ① (Repetitive and Non-Repetitive)	89	Amps
E_{AR}	Repetitive Avalanche Energy ①	50	mJ
E_{AS}	Single Pulse Avalanche Energy ④	3200	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage ($V_{GS} = 0\text{V}$, $I_D = 250\mu\text{A}$)	500			Volts
$I_{D(on)}$	On State Drain Current ② ($V_{DS} > I_{D(on)} \times R_{DS(on)}$ Max, $V_{GS} = 10\text{V}$)	89			Amps
$R_{DS(on)}$	Drain-Source On-State Resistance ② ($V_{GS} = 10\text{V}$, 0.5 $I_{D(\text{Cont.})}$)			0.050	Ohms
I_{DSS}	Zero Gate Voltage Drain Current ($V_{DS} = V_{DSS}$, $V_{GS} = 0\text{V}$)			250	μA
	Zero Gate Voltage Drain Current ($V_{DS} = 0.8 V_{DSS}$, $V_{GS} = 0\text{V}$, $T_C = 125^\circ\text{C}$)			1000	
I_{GSS}	Gate-Source Leakage Current ($V_{GS} = \pm 30\text{V}$, $V_{DS} = 0\text{V}$)			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 5\text{mA}$)	3		5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - <http://www.advancedpower.com>

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DYNAMIC CHARACTERISTICS

APT50M50L2FLL

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C_{iss}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1\text{ MHz}$		9840		pF
C_{oss}	Output Capacitance			2030		
C_{rss}	Reverse Transfer Capacitance			153		
Q_g	Total Gate Charge ^③	$V_{GS} = 10V$ $V_{DD} = 0.5 V_{DSS}$ $I_D = I_D[\text{Cont.}] @ 25^\circ C$		246		nC
Q_{gs}	Gate-Source Charge			65		
Q_{gd}	Gate-Drain ("Miller") Charge			112		
$t_d(\text{on})$	Turn-on Delay Time	$V_{GS} = 15V$ $V_{DD} = 0.5 V_{DSS}$ $I_D = I_D[\text{Cont.}] @ 25^\circ C$ $R_G = 0.6\Omega$		24		ns
t_r	Rise Time			22		
$t_d(\text{off})$	Turn-off Delay Time			56		
t_f	Fall Time			8		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I_S	Continuous Source Current (Body Diode)			89	Amps
I_{SM}	Pulsed Source Current ^① (Body Diode)			356	
V_{SD}	Diode Forward Voltage ^② ($V_{GS} = 0V$, $I_S = -I_D[\text{Cont.}]$)			1.3	Volts
dv/dt	Peak Diode Recovery dv/dt ^⑤			15	V/ns
t_{rr}	Reverse Recovery Time ($I_S = -I_D[\text{Cont.}]$, $di/dt = 100A/\mu s$)	$T_j = 25^\circ C$		300	ns
		$T_j = 125^\circ C$		600	
Q_{rr}	Reverse Recovery Charge ($I_S = -I_D[\text{Cont.}]$, $di/dt = 100A/\mu s$)	$T_j = 25^\circ C$		2.6	μC
		$T_j = 125^\circ C$		10	
I_{RRM}	Peak Recovery Current ($I_S = -I_D[\text{Cont.}]$, $di/dt = 100A/\mu s$)	$T_j = 25^\circ C$		17	Amps
		$T_j = 125^\circ C$		34	

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case			0.14	°C/W
$R_{\theta JA}$	Junction to Ambient			40	

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② Pulse Test: Pulse width < 380 μs , Duty Cycle < 2%

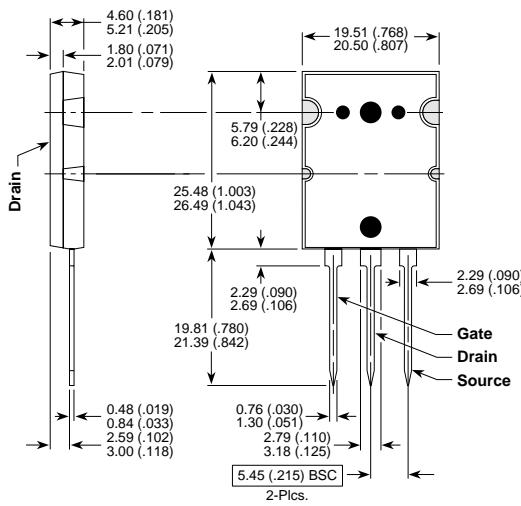
③ See MIL-STD-750 Method 3471

④ Starting $T_j = +25^\circ C$, $L = 0.81mH$, $R_G = 25\Omega$, Peak $I_L = 89A$

⑤ dv/dt numbers reflect the limitations of the test circuit rather than the device itself. $I_S \leq -I_D[\text{Cont.}]$ $di/dt \leq 700A/\mu s$ $V_R \leq V_{DSS}$ $T_j \leq 150^\circ C$

APT Reserves the right to change,
without notice, the specifications
and information contained herein.

TO-264 MAX™(L2) Package Outline



Dimensions in Millimeters and (Inches)

APT's devices are covered by one or more of the following U.S.patents: 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336
5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058